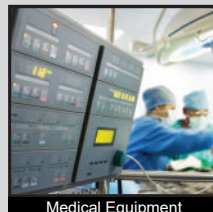
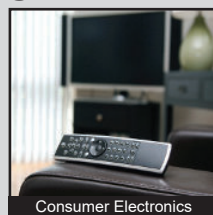
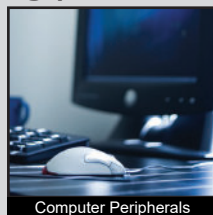


|                |                    |                     |                         |                   |                    |                    |                        |                        |                     |                 |                      |                         |
|----------------|--------------------|---------------------|-------------------------|-------------------|--------------------|--------------------|------------------------|------------------------|---------------------|-----------------|----------------------|-------------------------|
| CAP<br>OPTIONS | TOGGLE<br>SWITCHES | TACTILE<br>SWITCHES | SNAP ACTION<br>SWITCHES | SLIDE<br>SWITCHES | ROTARY<br>SWITCHES | ROCKER<br>SWITCHES | PUSHBUTTON<br>SWITCHES | NAVIGATION<br>SWITCHES | KEYLOCK<br>SWITCHES | DIP<br>SWITCHES | DETECTOR<br>SWITCHES | ANTI-VANDAL<br>SWITCHES |
|----------------|--------------------|---------------------|-------------------------|-------------------|--------------------|--------------------|------------------------|------------------------|---------------------|-----------------|----------------------|-------------------------|



# RoHS

## FEATURES & BENEFITS

- Up to 1,000,000 cycle life expectancy
- Tape and Reel packaging
- Surface mount design
- Actuation force options
- IP67 Rating

## PART NUMBER CONFIGURATOR

## Termination

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**J** - J-bend

Specifications subject to change without notice 8.17.2022



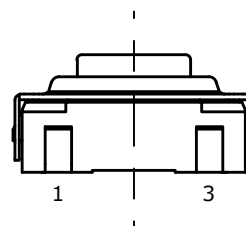
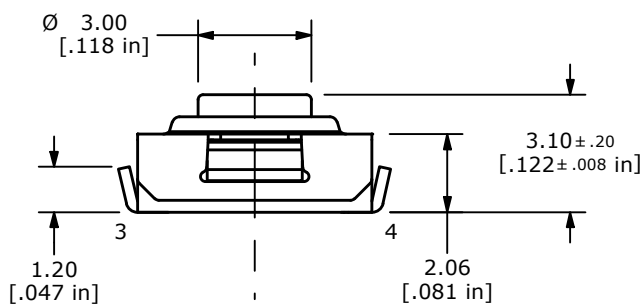
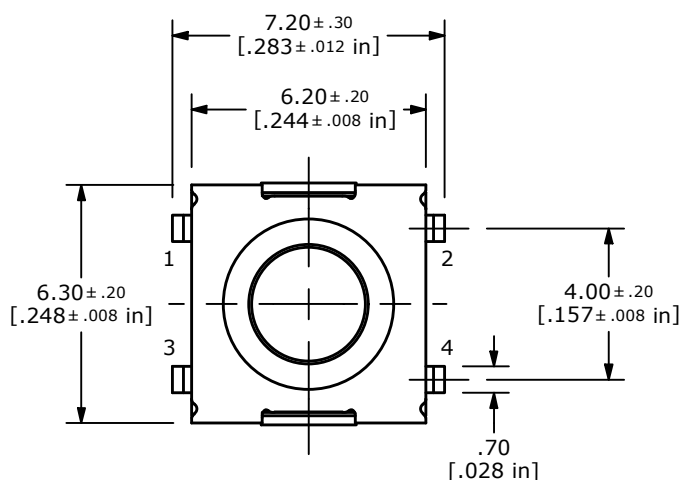
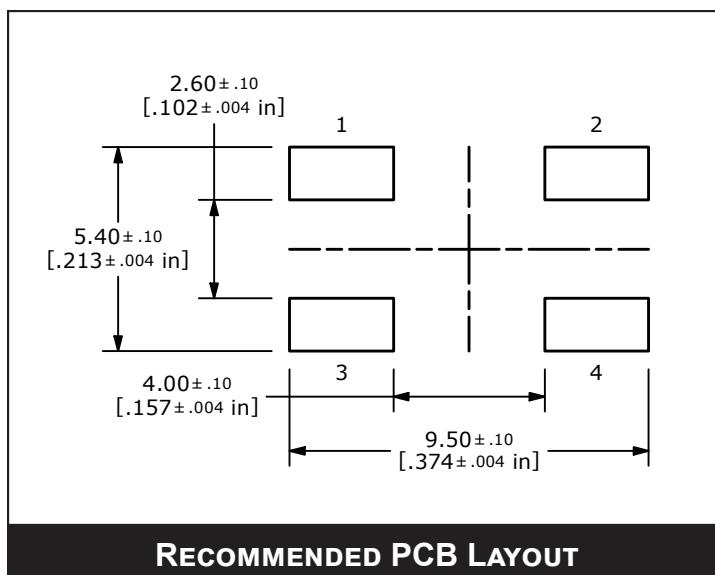
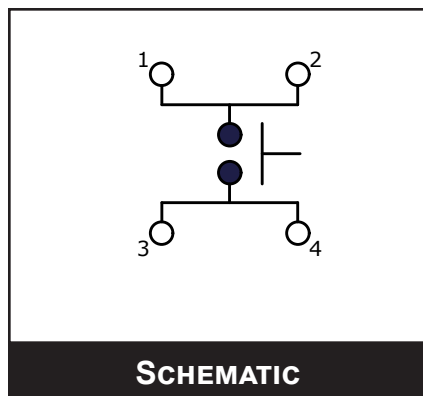
**E SWITCH®**

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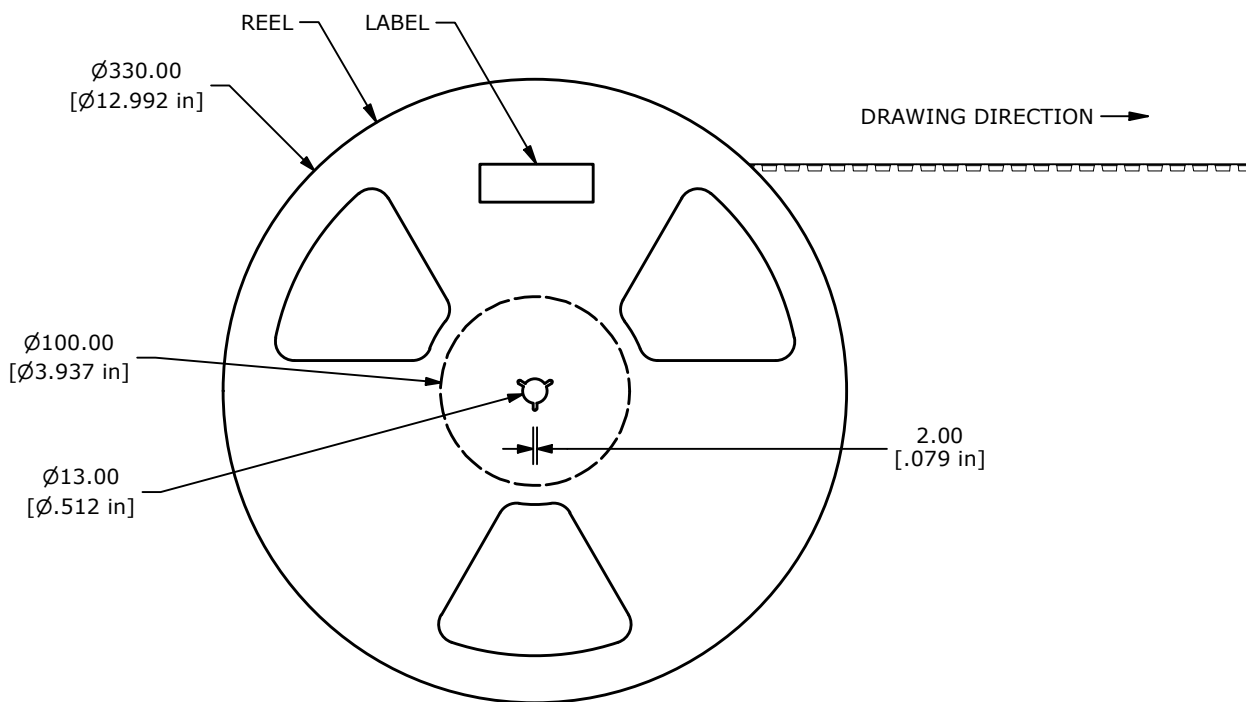
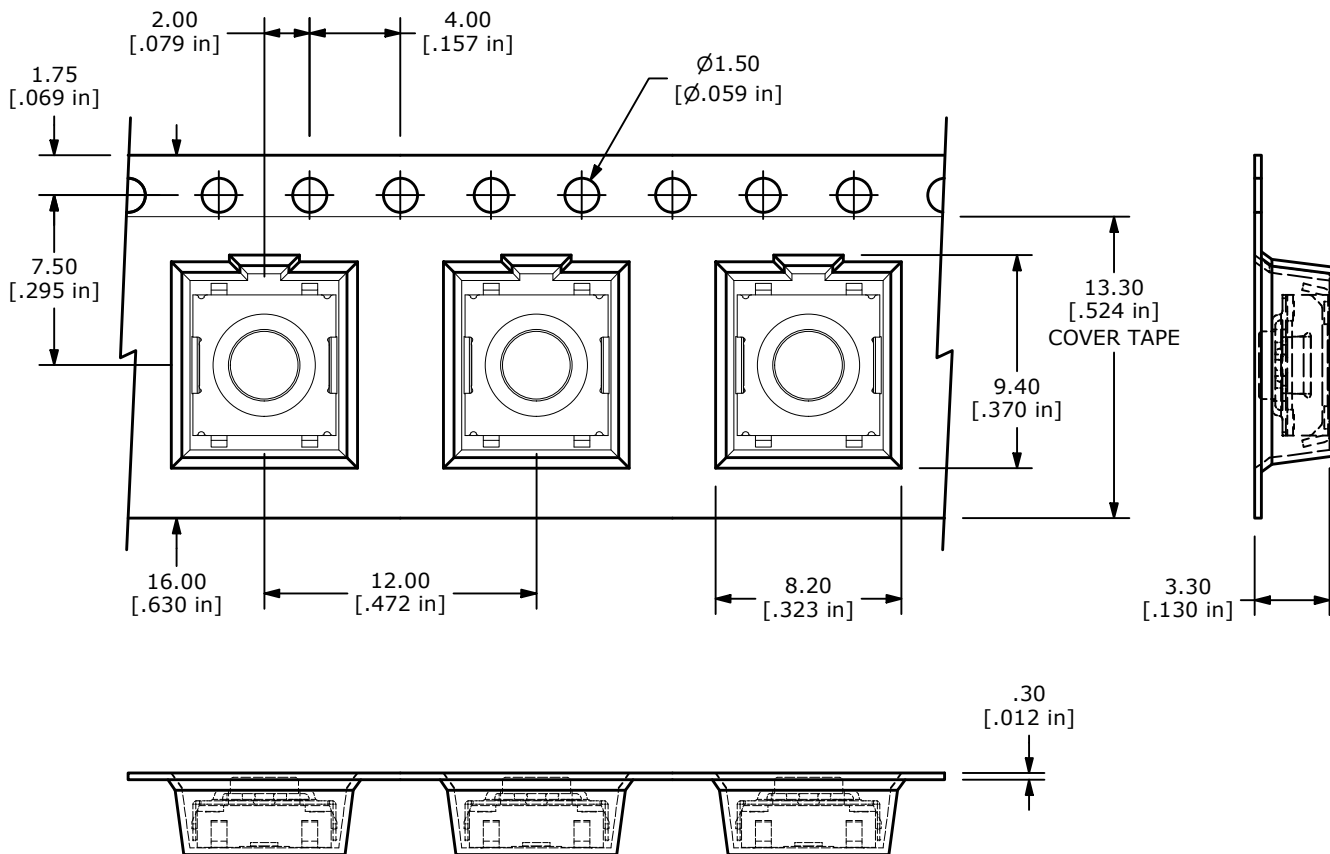
# TL6800 SERIES TACT SWITCH

## BODY DIMENSIONS



# TL6800 SERIES TACT SWITCH

## BODY DIMENSIONS TAPE AND REEL



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## RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

### “TYPICAL” SMT REFLOW (Pb and Pb-Free)

| Profile Feature                                       | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|-------------------------------------------------------|-------------------------|------------------|
| Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )       | 3 °C/second max.        | 3 °C/second max. |
| <b>Preheat</b>                                        |                         |                  |
| -Temperature Min ( $T_{s_{min}}$ )                    | 100 °C                  | 150 °C           |
| -Temperature Max ( $T_{s_{max}}$ )                    | 150 °C                  | 200 °C           |
| -Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )              | 60-120 seconds          | 60-180 seconds   |
| Time Maintained above:                                |                         |                  |
| -Temperature ( $T_L$ )                                | 183 °C                  | 217 °C           |
| -Time ( $t_L$ )                                       | 60-150 seconds          | 60-150 seconds   |
| Time within 5 °C of actual Peak Temperature ( $t_p$ ) | 10-30 seconds           | 20-40 seconds    |
| Ramp-Down Rate                                        | 6 °C/second max.        | 6 °C/second max. |
| Time 25 °C to Peak Temperature                        | 6 minutes max.          | 8 minutes max.   |

**Note 1:** All temperatures refer to topside of the package, measured on the package surface.

